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Systronic
Att. Mr P Pernot
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Our ref. ESA-TECQTM-LE-1042

Noordwijk, 07/09/2015

VISA: T Ghidini
CC: M Nikulainen, J-L Lortal (CNES)

Subject: Qualification Status of Systronic for Polyimide PCBs

Dear Mr Pernot,

Systronic submitted to ESTEC a rigid sequential polyimide PCB with heat sink and a rigid-flex multilayer polyimide PCB for qualification renewal. ESTEC reports the acceptable evaluation of both samples in QT8440 and QT8441.

Systronic has announced in SY-Q2-15 the delta qualification for two process changes in the manufacture of rigid-flex polyimide PCBs, which includes plasma etching of cover layer and an increase of lamination pressure. The aim is to increase the adhesion in the rigid-flex interface for specific complex designs. These process changes were included in the acceptable evaluation of report QT8441. The approval of the process changes is pending the successful outcome of Systronic's delta qualification.

The successful outcome of the audit of Systronic of April 2015 has been minuted in ESA-TECQTM-MIN-0785.

Systronic is considered qualified in accordance with ECSS-Q-ST-70-10C for the manufacture of printed circuit boards as follows:

Rigid sequential polyimide	as per PID 6 v8	**until 1-9-2017**
Rigid-flex sequential polyimide	as per PID 5 v8	**until 1-9-2017**

Best regards,
Stan Heltzel
Materials Technology Section TEC-QTM

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